

# BGA2817

MMIC wideband amplifier

Rev. 2 — 19 April 2012

Product data sheet

## 1. Product profile

### 1.1 General description

Silicon Monolithic Microwave Integrated Circuit (MMIC) wideband amplifier with internal matching circuit in a 6-pin SOT363 plastic SMD package.

### 1.2 Features and benefits

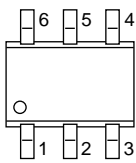
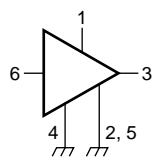
- Internally matched to  $50\ \Omega$
- A gain of 25.1 dB at 2150 MHz
- Output power at 1 dB gain compression = 5 dBm at 2150 MHz
- Supply current = 20.0 mA at a supply voltage of 3.3 V
- Reverse isolation > 35 dB up to 2150 MHz
- Good linearity with low second order and third order products
- Noise figure = 3.9 dB at 950 MHz
- Unconditionally stable ( $K > 1$ )
- No output inductor required

### 1.3 Applications

- LNB IF amplifiers
- General purpose low noise wideband amplifier for frequencies between DC and 2.2 GHz

## 2. Pinning information

Table 1. Pinning

Pin	Description	Simplified outline	Graphic symbol
1	$V_{CC}$		 sym052
2, 5	GND2		
3	RF_OUT		
4	GND1		
6	RF_IN		

### 3. Ordering information

Table 2. Ordering information

Type number	Package		
	Name	Description	Version
BGA2817	-	plastic surface-mounted package; 6 leads	SOT363

### 4. Marking

Table 3. Marking

Type number	Marking code	Description
BGA2817	LS*	* = - : made in Hong Kong * = p : made in Hong Kong * = W : made in China * = t : made in Malaysia

### 5. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CC}$	supply voltage	RF input AC coupled	-0.5	4.5	V
$I_{CC}$	supply current		-	55	mA
$P_{tot}$	total power dissipation	$T_{sp} = 90\text{ °C}$	-	200	mW
$T_{stg}$	storage temperature		-40	+125	°C
$T_j$	junction temperature		-	125	°C
$P_{drive}$	drive power		-	-16.5	dBm

### 6. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Typ	Unit
$R_{th(j-sp)}$	thermal resistance from junction to solder point	$P_{tot} = 200\text{ mW}$ ; $T_{sp} = 90\text{ °C}$	300	K/W

### 7. Characteristics

Table 6. Characteristics

$V_{CC} = 3.3\text{ V}$ ;  $Z_S = Z_L = 50\ \Omega$ ;  $P_i = -40\text{ dBm}$ ;  $T_{amb} = 25\text{ °C}$ ; measured on demo board; unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{CC}$	supply voltage		3.0	3.3	3.6	V
$I_{CC}$	supply current		17.6	20.0	22.2	mA

**Table 6. Characteristics ...continued**

$V_{CC} = 3.3\text{ V}$ ;  $Z_S = Z_L = 50\ \Omega$ ;  $P_i = -40\text{ dBm}$ ;  $T_{amb} = 25\text{ }^\circ\text{C}$ ; measured on demo board; unless otherwise specified.

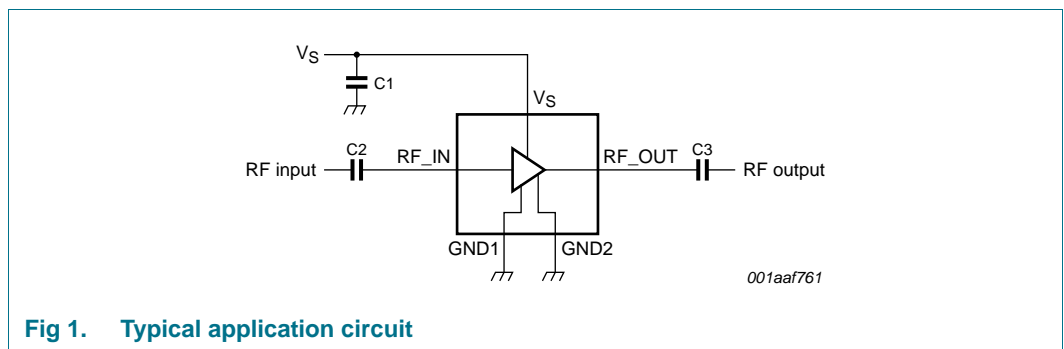
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
G <sub>p</sub>	power gain	f = 250 MHz	23.9	24.5	25.1	dB
		f = 950 MHz	23.9	24.7	25.4	dB
		f = 2150 MHz	23.7	25.1	26.6	dB
RL <sub>in</sub>	input return loss	f = 250 MHz	13	15	17	dB
		f = 950 MHz	14	16	18	dB
		f = 2150 MHz	12	19	26	dB
RL <sub>out</sub>	output return loss	f = 250 MHz	13	18	22	dB
		f = 950 MHz	17	18	19	dB
		f = 2150 MHz	12	15	18	dB
ISL	isolation	f = 250 MHz	48	69	89	dB
		f = 950 MHz	47	49	50	dB
		f = 2150 MHz	33	35	37	dB
NF	noise figure	f = 250 MHz	3.4	3.9	4.4	dB
		f = 950 MHz	3.5	3.9	4.3	dB
		f = 2150 MHz	3.4	3.8	4.2	dB
B <sub>-3dB</sub>	-3 dB bandwidth	3 dB below gain at 1 GHz	3.2	3.4	3.6	GHz
K	Rollett stability factor	f = 250 MHz	51	78	106	
		f = 950 MHz	6	8	9	
		f = 2150 MHz	1	2	2	
P <sub>L(sat)</sub>	saturated output power	f = 250 MHz	8	8	9	dBm
		f = 950 MHz	5	7	8	dBm
		f = 2150 MHz	5	6	7	dBm
P <sub>L(1dB)</sub>	output power at 1 dB gain compression	f = 250 MHz	6	6	7	dBm
		f = 950 MHz	5	6	7	dBm
		f = 2150 MHz	4	5	7	dBm
IP3 <sub>I</sub>	input third-order intercept point	P <sub>drive</sub> = -40 dBm (for each tone)				
		f <sub>1</sub> = 250 MHz; f <sub>2</sub> = 251 MHz	-9	-7	-5	dBm
		f <sub>1</sub> = 950 MHz; f <sub>2</sub> = 951 MHz	-9	-7	-5	dBm
		f <sub>1</sub> = 2150 MHz; f <sub>2</sub> = 2151 MHz	-13	-10	-7	dBm
IP3 <sub>O</sub>	output third-order intercept point	P <sub>drive</sub> = -40 dBm (for each tone)				
		f <sub>1</sub> = 250 MHz; f <sub>2</sub> = 251 MHz	16	18	20	dBm
		f <sub>1</sub> = 950 MHz; f <sub>2</sub> = 951 MHz	16	18	20	dBm
		f <sub>1</sub> = 2150 MHz; f <sub>2</sub> = 2151 MHz	12	15	18	dBm
P <sub>L(2H)</sub>	second harmonic output power	P <sub>drive</sub> = -28 dBm				
		f <sub>1H</sub> = 250 MHz; f <sub>2H</sub> = 500 MHz	-55	-53	-51	dBm
		f <sub>1H</sub> = 950 MHz; f <sub>2H</sub> = 1900 MHz	-47	-45	-44	dBm
ΔIM2	second-order intermodulation distance	P <sub>drive</sub> = -31 dBm (for each tone)				
		f <sub>1</sub> = 250 MHz; f <sub>2</sub> = 251 MHz	34	36	39	dBc
		f <sub>1</sub> = 950 MHz; f <sub>2</sub> = 951 MHz	38	39	41	dBc

## 8. Application information

[Figure 1](#) shows a typical application circuit for the BGA2817 MMIC. The device is internally matched to 50 Ω, and therefore does not need any external matching. The value of the input and output DC blocking capacitors C2 and C3 should not be more than 100 pF for applications above 100 MHz. However, when the device is operated below 100 MHz, the capacitor value should be increased.

The 22 nF supply decoupling capacitor C1 should be located as close as possible to the MMIC.

The PCB top ground plane, connected to pins 2, 4 and 5 must be as close as possible to the MMIC, preferably also below the MMIC. When using via holes, use multiple via holes as close as possible to the MMIC.



**Fig 1. Typical application circuit**

### 8.1 Application examples

The MMIC is very suitable as IF amplifier in e.g. LNB's. The excellent wideband characteristics make it an easy building block.

As second amplifier after an LNA, the MMIC offers an easy matching, low noise solution.

### 8.2 Tables

**Table 7. Supply current over temperature and supply voltages**  
Typical values.

Symbol	Parameter	Conditions	T <sub>amb</sub> (°C)			Unit
			-40	25	85	
I <sub>CC</sub>	supply current	V <sub>CC</sub> = 3.0 V	18.0	17.6	17.3	mA
		V <sub>CC</sub> = 3.3 V	20.4	20.0	19.6	mA
		V <sub>CC</sub> = 3.6 V	22.7	22.2	21.7	mA

**Table 8. Second harmonic output power over temperature and supply voltages**  
*Typical values.*

Symbol	Parameter	Conditions	T <sub>amb</sub> (°C)			Unit
			-40	25	85	
P <sub>L(2H)</sub>	second harmonic output power	f = 250 MHz; P <sub>drive</sub> = -28 dBm				
		V <sub>CC</sub> = 3.0 V	-38	-44	-52	dBm
		V <sub>CC</sub> = 3.3 V	-45	-53	-60	dBm
		V <sub>CC</sub> = 3.6 V	-56	-59	-53	dBm
		f = 950 MHz; P <sub>drive</sub> = -28 dBm				
		V <sub>CC</sub> = 3.0 V	-43	-53	-45	dBm
		V <sub>CC</sub> = 3.3 V	-51	-45	-41	dBm
		V <sub>CC</sub> = 3.6 V	-44	-41	-39	dBm

**Table 9. Input power at 1 dB gain compression over temperature and supply voltages**  
*Typical values.*

Symbol	Parameter	Conditions	T <sub>amb</sub> (°C)			Unit
			-40	25	85	
P <sub>i(1dB)</sub>	input power at 1 dB gain compression	f = 250 MHz				
		V <sub>CC</sub> = 3.0 V	-19	-18	-18	dBm
		V <sub>CC</sub> = 3.3 V	-17	-17	-17	dBm
		V <sub>CC</sub> = 3.6 V	-16	-16	-16	dBm
		f = 950 MHz				
		V <sub>CC</sub> = 3.0 V	-19	-18	-18	dBm
		V <sub>CC</sub> = 3.3 V	-18	-17	-17	dBm
		V <sub>CC</sub> = 3.6 V	-17	-17	-17	dBm
		f = 2150 MHz				
		V <sub>CC</sub> = 3.0 V	-20	-20	-20	dBm
		V <sub>CC</sub> = 3.3 V	-19	-19	-20	dBm
		V <sub>CC</sub> = 3.6 V	-18	-19	-20	dBm

**Table 10. Output power at 1 dB gain compression over temperature and supply voltages**  
Typical values.

Symbol	Parameter	Conditions	T <sub>amb</sub> (°C)			Unit
			-40	25	85	
P <sub>L(1dB)</sub>	output power at 1 dB gain compression	f = 250 MHz				
		V <sub>CC</sub> = 3.0 V	4	5	5	dBm
		V <sub>CC</sub> = 3.3 V	6	6	6	dBm
		V <sub>CC</sub> = 3.6 V	8	8	7	dBm
		f = 950 MHz				
		V <sub>CC</sub> = 3.0 V	4	4	4	dBm
		V <sub>CC</sub> = 3.3 V	6	6	6	dBm
		V <sub>CC</sub> = 3.6 V	7	7	7	dBm
		f = 2150 MHz				
		V <sub>CC</sub> = 3.0 V	4	4	3	dBm
		V <sub>CC</sub> = 3.3 V	6	5	4	dBm
		V <sub>CC</sub> = 3.6 V	7	6	5	dBm

**Table 11. Saturated output power over temperature and supply voltages**  
Typical values.

Symbol	Parameter	Conditions	T <sub>amb</sub> (°C)			Unit
			-40	25	85	
P <sub>L(sat)</sub>	saturated output power	f = 250 MHz				
		V <sub>CC</sub> = 3.0 V	6	6	7	dBm
		V <sub>CC</sub> = 3.3 V	8	8	8	dBm
		V <sub>CC</sub> = 3.6 V	9	9	9	dBm
		f = 950 MHz				
		V <sub>CC</sub> = 3.0 V	6	6	6	dBm
		V <sub>CC</sub> = 3.3 V	7	7	7	dBm
		V <sub>CC</sub> = 3.6 V	7	8	8	dBm
		f = 2150 MHz				
		V <sub>CC</sub> = 3.0 V	5	5	4	dBm
		V <sub>CC</sub> = 3.3 V	7	6	5	dBm
		V <sub>CC</sub> = 3.6 V	8	7	6	dBm

**Table 12. Second-order intermodulation distance over temperature and supply voltages**  
Typical values.

Symbol	Parameter	Conditions	T <sub>amb</sub> (°C)			Unit	
			-40	25	85		
ΔIM2	second-order intermodulation distance	f <sub>1</sub> = 250 MHz; f <sub>2</sub> = 251 MHz; P <sub>drive</sub> = -31 dBm	V <sub>CC</sub> = 3.0 V	28	32	36	dBc
			V <sub>CC</sub> = 3.3 V	33	36	40	dBc
			V <sub>CC</sub> = 3.6 V	38	40	44	dBc
		f <sub>1</sub> = 950 MHz; f <sub>2</sub> = 951 MHz; P <sub>drive</sub> = -31 dBm	V <sub>CC</sub> = 3.0 V	29	34	40	dBc
			V <sub>CC</sub> = 3.3 V	35	39	43	dBc
			V <sub>CC</sub> = 3.6 V	40	44	42	dBc

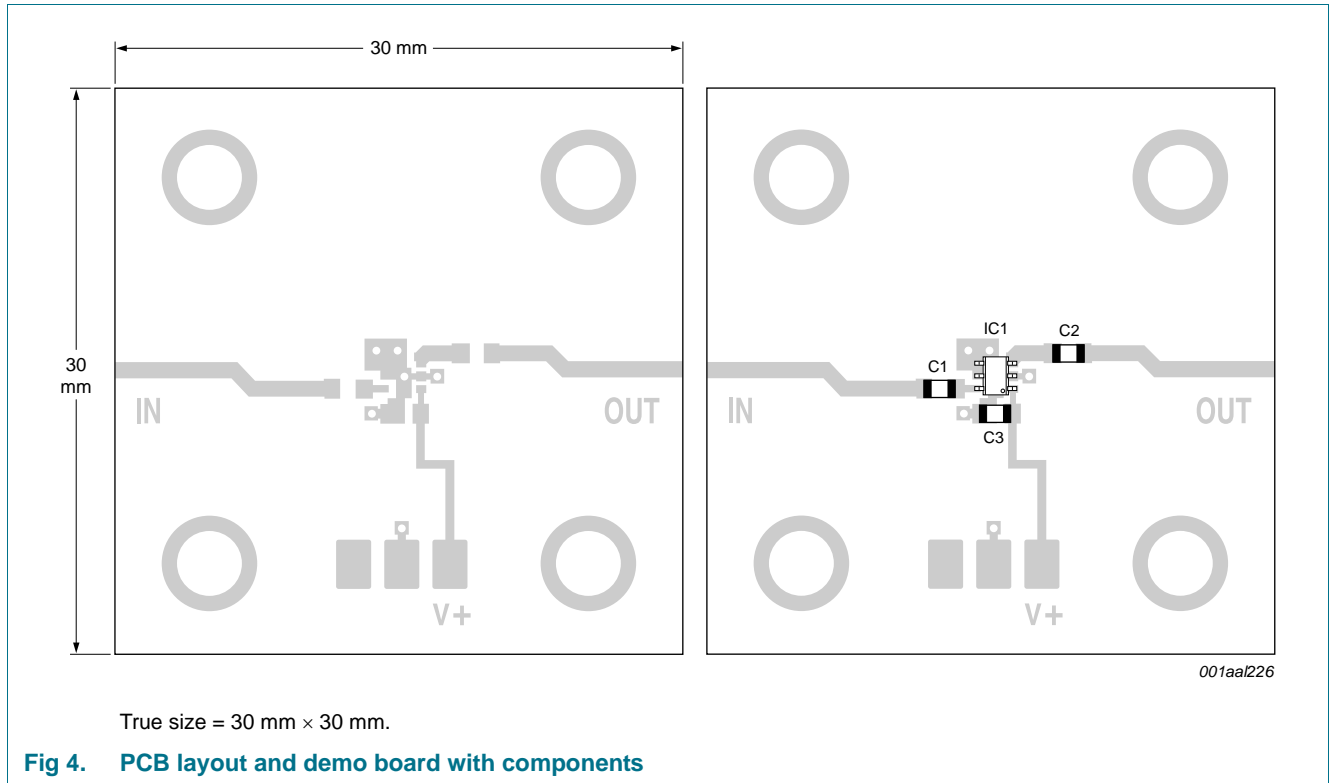
**Table 13. Output third-order intercept point over temperature and supply voltages**  
Typical values.

Symbol	Parameter	Conditions	T <sub>amb</sub> (°C)			Unit	
			-40	25	85		
IP3 <sub>O</sub>	output third-order intercept point	f <sub>1</sub> = 250 MHz; f <sub>2</sub> = 251 MHz; P <sub>drive</sub> = -40 dBm	V <sub>CC</sub> = 3.0 V	14	15	16	dBm
			V <sub>CC</sub> = 3.3 V	18	18	17	dBm
			V <sub>CC</sub> = 3.6 V	19	19	19	dBm
		f <sub>1</sub> = 950 MHz; f <sub>2</sub> = 951 MHz; P <sub>drive</sub> = -40 dBm	V <sub>CC</sub> = 3.0 V	15	16	15	dBm
			V <sub>CC</sub> = 3.3 V	18	18	17	dBm
			V <sub>CC</sub> = 3.6 V	20	20	18	dBm
		f <sub>1</sub> = 2150 MHz; f <sub>2</sub> = 2151 MHz; P <sub>drive</sub> = -40 dBm	V <sub>CC</sub> = 3.0 V	15	14	12	dBm
			V <sub>CC</sub> = 3.3 V	17	15	13	dBm
			V <sub>CC</sub> = 3.6 V	18	16	13	dBm

**Table 14. -3 dB bandwidth over temperature and supply voltages**  
Typical values.

Symbol	Parameter	Conditions	T <sub>amb</sub> (°C)			Unit
			-40	25	85	
B <sub>-3dB</sub>	-3 dB bandwidth	V <sub>CC</sub> = 3.0 V	3.50	3.39	3.24	GHz
		V <sub>CC</sub> = 3.3 V	3.49	3.37	3.22	GHz
		V <sub>CC</sub> = 3.6 V	3.48	3.36	3.21	GHz

**9. Test information**



**Table 15. List of components used for the typical application**

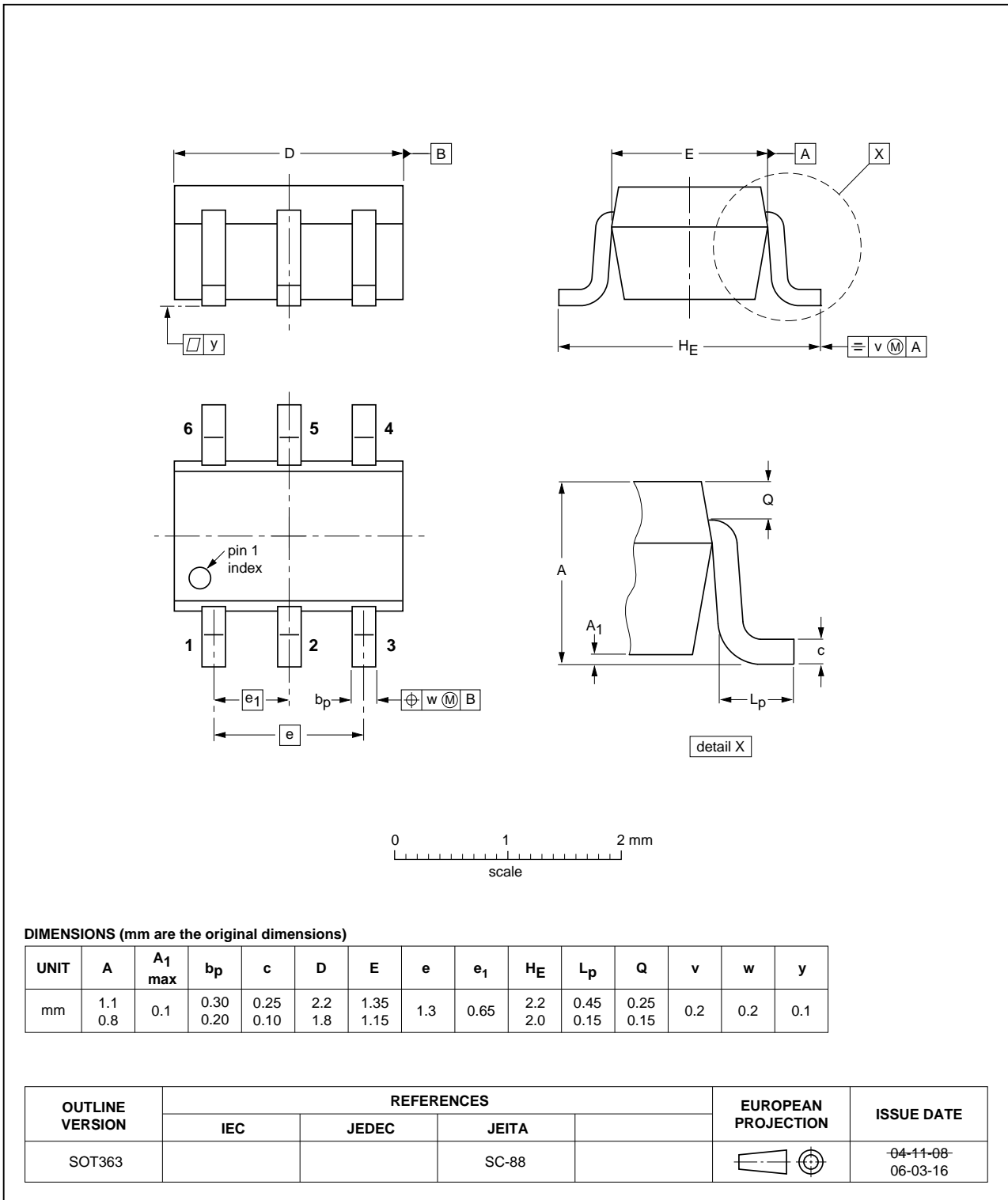
Component	Description	Value	Dimensions
C1, C2	multilayer ceramic chip capacitor	100 pF	0603
C3	multilayer ceramic chip capacitor	22 nF	0603
IC1	BGA2817 MMIC		SOT363



**10. Package outline**

Plastic surface-mounted package; 6 leads

SOT363



**Fig 5. Package outline SOT363**

## 11. Abbreviations

**Table 16. Abbreviations**

Acronym	Description
DC	Direct Current
IF	Intermediate Frequency
LNA	Low-Noise Amplifier
LNB	Low-Noise Block converter
PCB	Printed-Circuit Board
RF	Radio Frequency
SMD	Surface Mounted Device

## 12. Revision history

**Table 17. Revision history**

Document ID	Release date	Data sheet status	Change notice	Supersedes
BGA2817 v.2	20120419	Product data sheet	-	BGA2817 v.1
Modifications	<ul style="list-style-type: none"><li>• <a href="#">Table 5 on page 2</a>: The maximum value for <math>V_{CC}</math> has been changed to 4.5 V</li></ul>			
BGA2817 v.1	20111117	Product data sheet	-	-

## 13. Legal information

### 13.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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